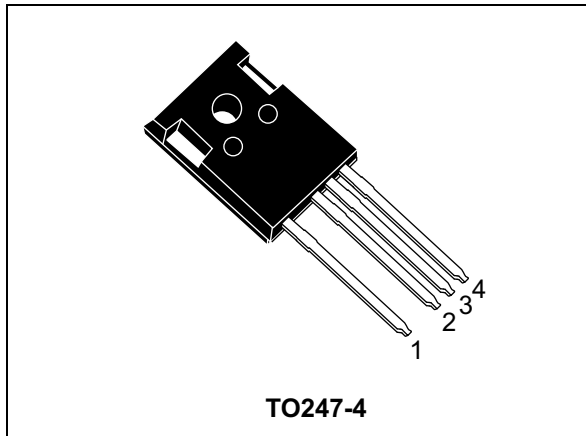
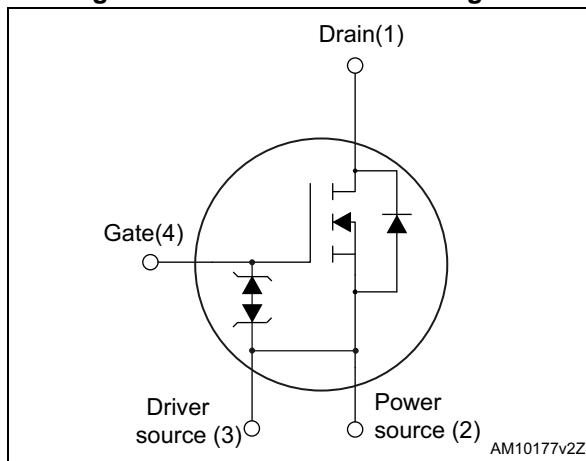


## N-channel 650 V, 0.049 $\Omega$ typ., 49 A MDmesh™ M2 Power MOSFET in a TO247-4 package

Datasheet - production data



**Figure 1. Internal schematic diagram**



### Features

| Order code   | V <sub>DS</sub> | R <sub>DS(on)</sub> max | I <sub>D</sub> |
|--------------|-----------------|-------------------------|----------------|
| STW56N65M2-4 | 650 V           | 0.062 $\Omega$          | 49 A           |

- Excellent switching performance thanks to the extra driving source pin
- Extremely low gate charge
- Excellent output capacitance (C<sub>oss</sub>) profile
- 100% avalanche tested
- Zener-protected

### Applications

- Switching applications

### Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.

**Table 1. Device summary**

| Order code   | Marking | Package | Packaging |
|--------------|---------|---------|-----------|
| STW56N65M2-4 | 56N65M2 | TO247-4 | Tube      |

# Contents

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- 2      Electrical characteristics ..... 4**
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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

| Symbol         | Parameter   | Value       | Unit             |
|----------------|---|-------------|------------------|
| $V_{GS}$       | Gate- source voltage  | $\pm 25$    | V                |
| $I_D$          | Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$  | 49          | A                |
| $I_D$          | Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$ | 31          | A                |
| $I_{DM}^{(1)}$ | Drain current (pulsed)  | 196         | A                |
| $P_{TOT}$      | Total dissipation at $T_C = 25\text{ }^\circ\text{C}$           | 358         | W                |
| $dv/dt^{(2)}$  | Peak diode recovery voltage slope                               | 15          | V/ns             |
| $dv/dt^{(3)}$  | MOSFET $dv/dt$ ruggedness                                       | 50          | V/ns             |
| $T_{stg}$      | Storage temperature   | - 55 to 150 | $^\circ\text{C}$ |
| $T_j$          | Max. operating junction temperature                             | 150         | $^\circ\text{C}$ |

1. Pulse width limited by safe operating area
2.  $I_{SD} \leq 49\text{ A}$ ,  $di/dt = 400\text{ A}/\mu\text{s}$ ,  $V_{DS(\text{peak})} < V_{(BR)DSS}$ ,  $V_{DD} = 400\text{ V}$
3.  $V_{DS} \leq 520\text{ V}$

**Table 3. Thermal data**

| Symbol         | Parameter                               | Value | Unit                      |
|----------------|---|-------|---------------------------|
| $R_{thj-amb}$  | Thermal resistance junction-ambient max | 50    | $^\circ\text{C}/\text{W}$ |
| $R_{thj-case}$ | Thermal resistance junction-case max    | 0.35  | $^\circ\text{C}/\text{W}$ |

**Table 4. Avalanche characteristics**

| Symbol   | Parameter  | Value | Unit |
|----------|--|-------|------|
| $I_{AR}$ | Max current during repetitive or single pulse avalanche (pulse width limited by $T_{JMAX}$ )                         | 3.5   | A    |
| $E_{AS}$ | Single pulse avalanche energy (starting $T_j = 25\text{ }^\circ\text{C}$ , $I_D = I_{AR}$ , $V_{DD} = 50\text{ V}$ ) | 1300  | mJ   |

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 5. On /off states**

| Symbol        | Parameter  | Test conditions  | Min. | Typ.  | Max.     | Unit                           |
|---------------|--|--|------|-------|----------|--------------------------------|
| $V_{(BR)DSS}$ | Drain-source breakdown voltage                   | $I_D = 1\text{ mA}$ , $V_{GS} = 0$   | 650  |       |          | V                              |
| $I_{DSS}$     | Zero gate voltage drain current ( $V_{GS} = 0$ ) | $V_{DS} = 650\text{ V}$<br>$V_{DS} = 650\text{ V}$ , $T_C = 125\text{ °C}$ |      |       | 1<br>100 | $\mu\text{A}$<br>$\mu\text{A}$ |
| $I_{GSS}$     | Gate-body leakage current ( $V_{DS} = 0$ )       | $V_{GS} = \pm 25\text{ V}$   |      |       | $\pm 10$ | nA                             |
| $V_{GS(th)}$  | Gate threshold voltage                           | $V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$                         | 2    | 3     | 4        | V                              |
| $R_{DS(on)}$  | Static drain-source on-resistance                | $V_{GS} = 10\text{ V}$ , $I_D = 24.5\text{ A}$                             |      | 0.049 | 0.062    | $\Omega$                       |

**Table 6. Dynamic**

| Symbol            | Parameter                     | Test conditions  | Min. | Typ. | Max. | Unit     |
|-------------------|-------------------------------|--|------|------|------|----------|
| $C_{iss}$         | Input capacitance             | $V_{DS} = 100\text{ V}$ , $f = 1\text{ MHz}$ ,<br>$V_{GS} = 0$   | -    | 3900 | -    | pF       |
| $C_{oss}$         | Output capacitance            |  | -    | 160  | -    | pF       |
| $C_{riss}$        | Reverse transfer capacitance  |  | -    | 2.8  | -    | pF       |
| $C_{o(er)}^{(1)}$ | Equivalent Output Capacitance | $V_{GS} = 0$ , $V_{DS} = 0\text{ to }520\text{ V}$   | -    | 838  | -    | pF       |
| $R_G$             | Intrinsic gate resistance     | $f = 1\text{ MHz}$ open drain  | -    | 4.6  | -    | $\Omega$ |
| $Q_g$             | Total gate charge             | $V_{DD} = 520\text{ V}$ , $I_D = 49\text{ A}$ ,<br>$V_{GS} = 10\text{ V}$ , (see <a href="#">Figure 15</a> ) | -    | 93   | -    | nC       |
| $Q_{gs}$          | Gate-source charge            |  | -    | 16   | -    | nC       |
| $Q_{gd}$          | Gate-drain charge             |  | -    | 40   | -    | nC       |

1.  $C_{oss}$  eq. is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

Table 7. Switching times

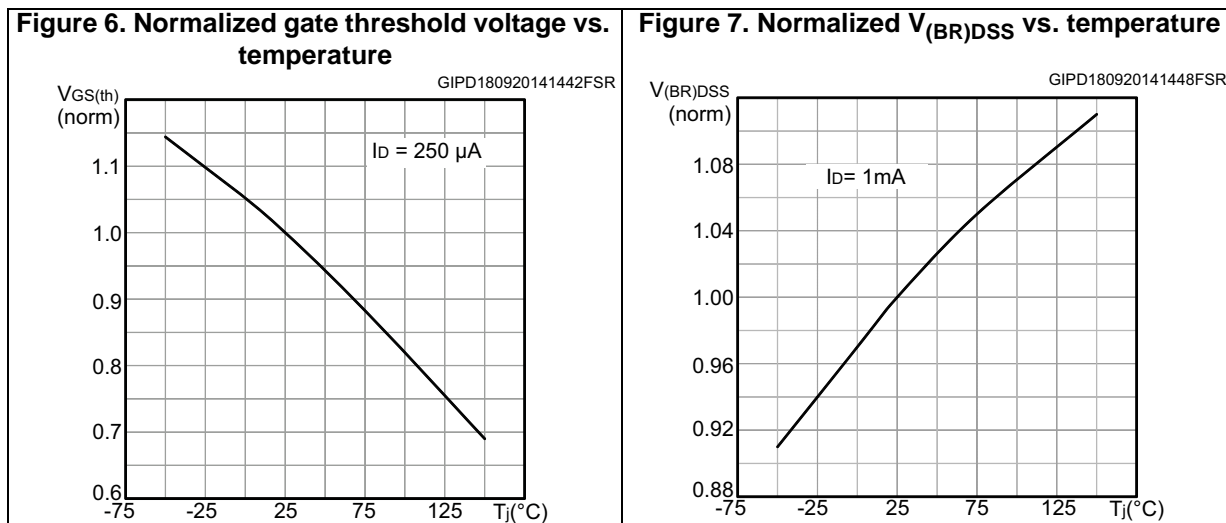
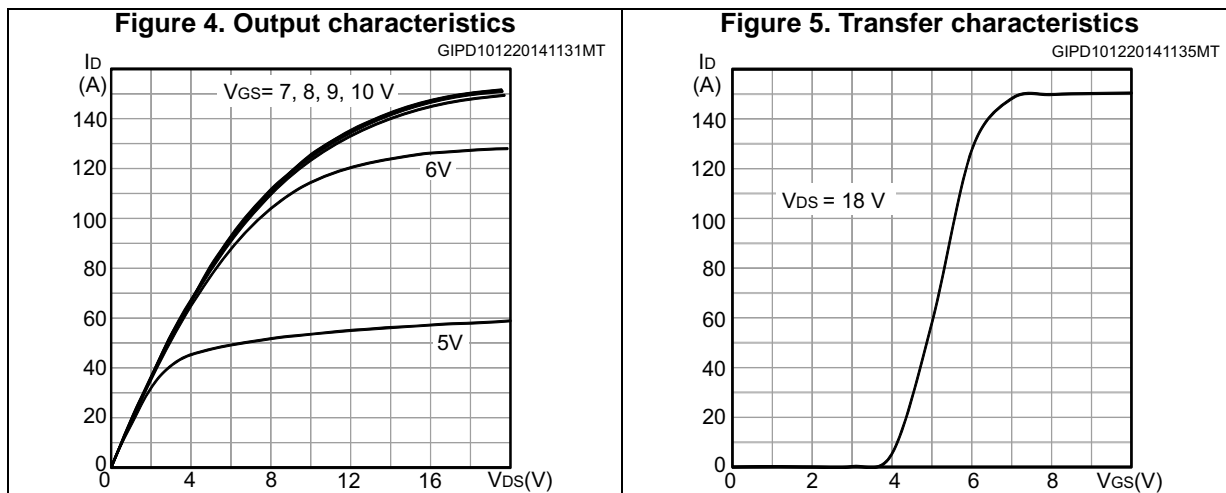
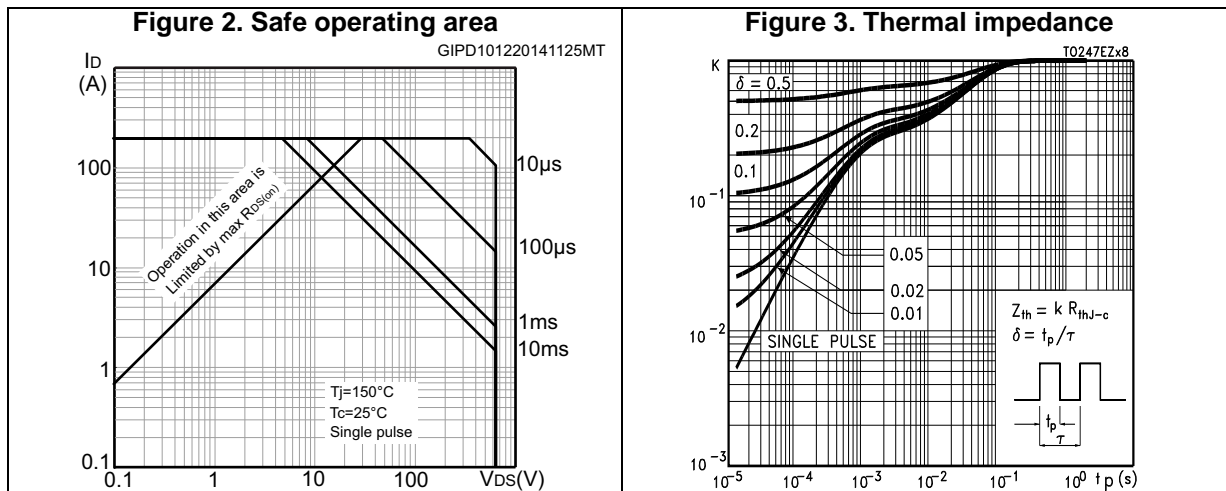
| Symbol       | Parameter           | Test conditions  | Min. | Typ. | Max. | Unit |
|--------------|---------------------|--|------|------|------|------|
| $t_{d(on)}$  | Turn-on delay time  | $V_{DD} = 325\text{ V}$ , $I_D = 24.5\text{ A}$ ,<br>$R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$<br>(see <a href="#">Figure 16</a> and<br><a href="#">Figure 19</a> ) | -    | 19   | -    | ns   |
| $t_r$        | Rise time           |  | -    | 27.5 | -    | ns   |
| $t_{d(off)}$ | Turn-off delay time |  | -    | 146  | -    | ns   |
| $t_f$        | Fall time           |  | -    | 13   | -    | ns   |

Table 8. Source drain diode

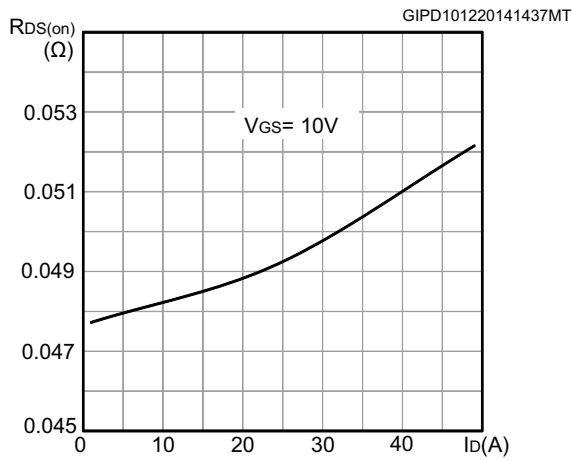
| Symbol          | Parameter                     | Test conditions  | Min. | Typ. | Max. | Unit          |
|-----------------|-------------------------------|--|------|------|------|---------------|
| $I_{SD}$        | Source-drain current          |  | -    |      | 49   | A             |
| $I_{SDM}^{(1)}$ | Source-drain current (pulsed) |  | -    |      | 196  | A             |
| $V_{SD}^{(2)}$  | Forward on voltage            | $I_{SD} = 49\text{ A}$ , $V_{GS} = 0$  | -    |      | 1.6  | V             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 49\text{ A}$ ,<br>$di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 60\text{ V}$ (see <a href="#">Figure 16</a> )  | -    | 554  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |  | -    | 13.5 |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |  | -    | 49.5 |      | A             |
| $t_{rr}$        | Reverse recovery time         | $I_{SD} = 49\text{ A}$ ,<br>$di/dt = 100\text{ A}/\mu\text{s}$<br>$V_{DD} = 60\text{ V}$ , $T_j = 150\text{ }^\circ\text{C}$<br>(see <a href="#">Figure 19</a> ) | -    | 688  |      | ns            |
| $Q_{rr}$        | Reverse recovery charge       |  | -    | 18   |      | $\mu\text{C}$ |
| $I_{RRM}$       | Reverse recovery current      |  | -    | 52   |      | A             |

1. Pulse width limited by safe operating area
2. Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%

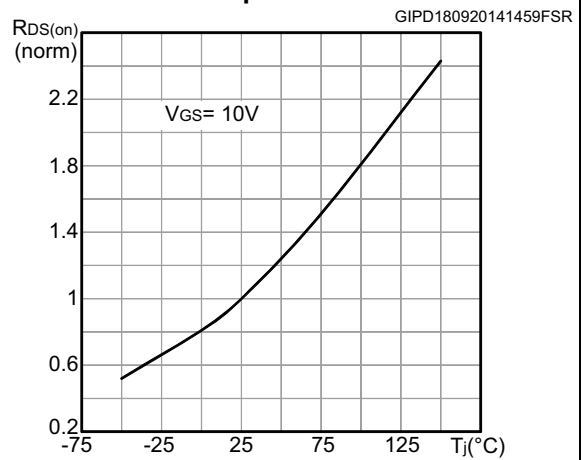
## 2.1 Electrical characteristics (curves)



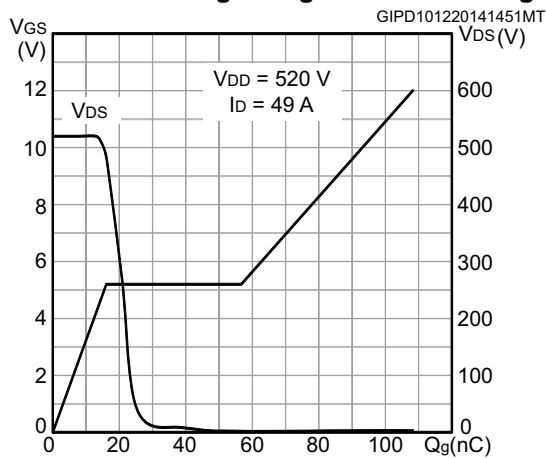
**Figure 8. Static drain-source on-resistance**



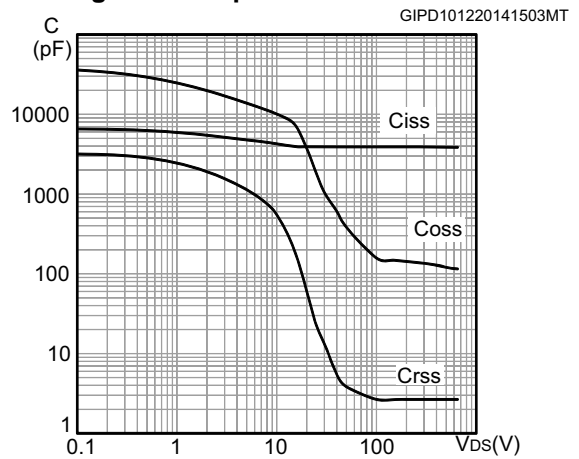
**Figure 9. Normalized on-resistance vs. temperature**



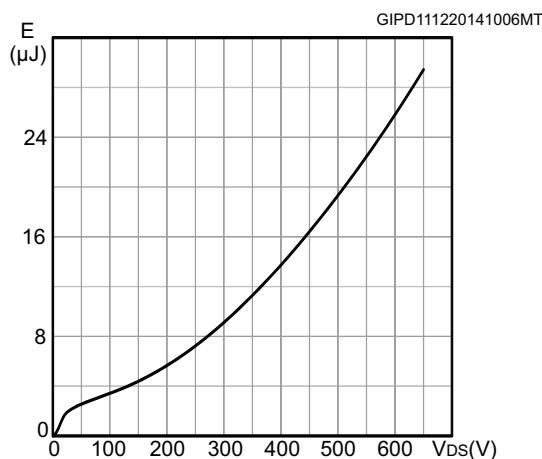
**Figure 10. Gate charge vs. gate-source voltage**



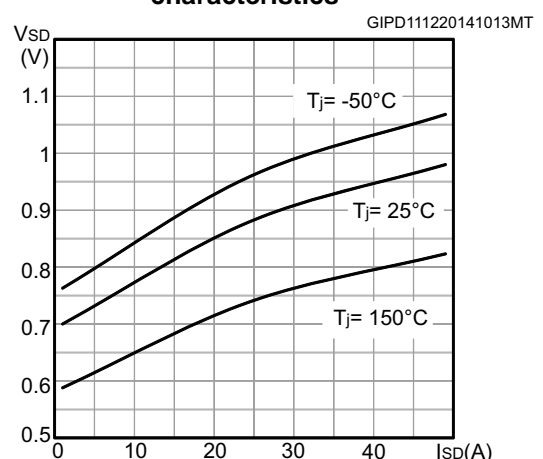
**Figure 11. Capacitance variations**



**Figure 12. Output capacitance stored energy**

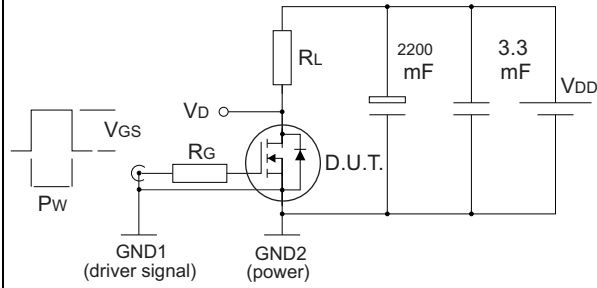


**Figure 13. Source-drain diode forward characteristics**



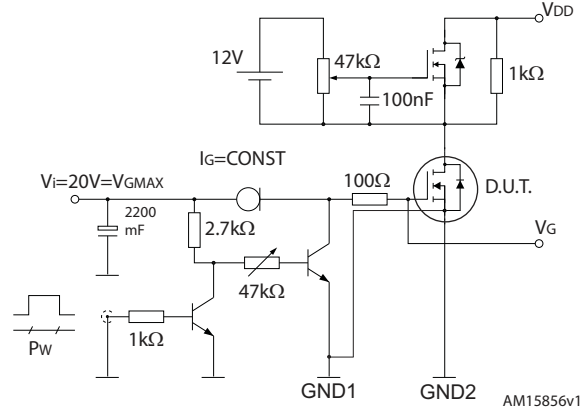
### 3 Test circuits

**Figure 14. Switching times test circuit for resistive load**



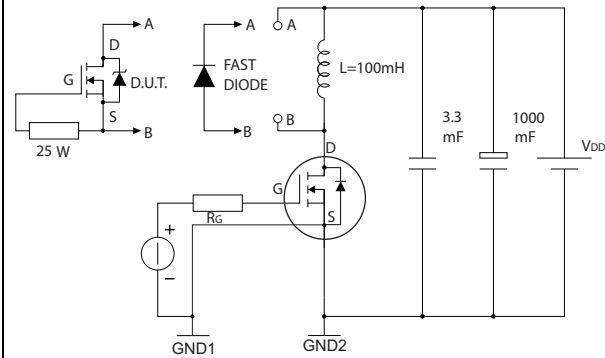
AM15855v1

**Figure 15. Gate charge test circuit**



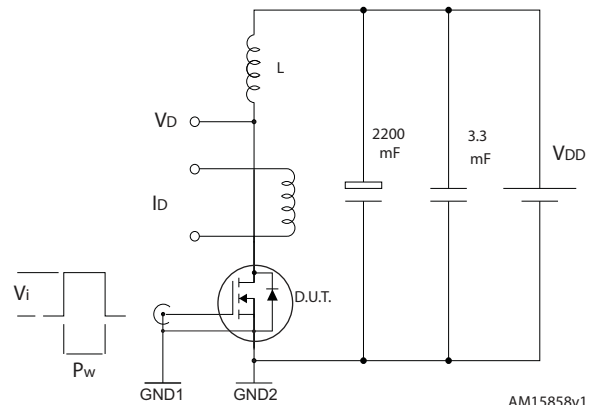
AM15856v1

**Figure 16. Test circuit for inductive load switching and diode recovery times**



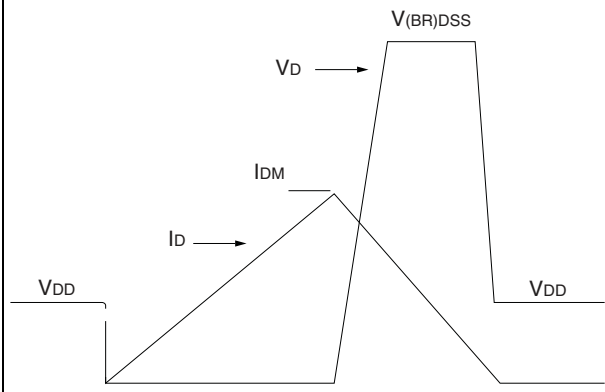
AM15857v1

**Figure 17. Unclamped inductive load test circuit**



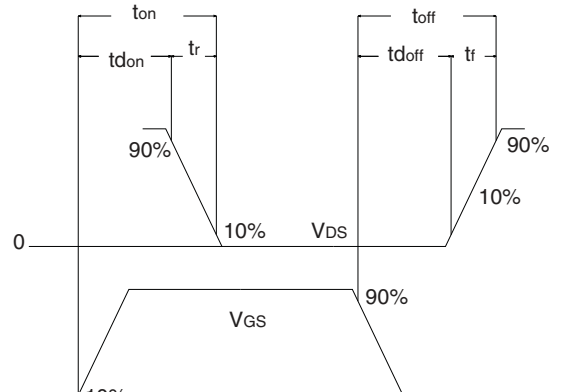
AM15858v1

**Figure 18. Unclamped inductive waveform**



AM01472v1

**Figure 19. Switching time waveform**



AM01473v1

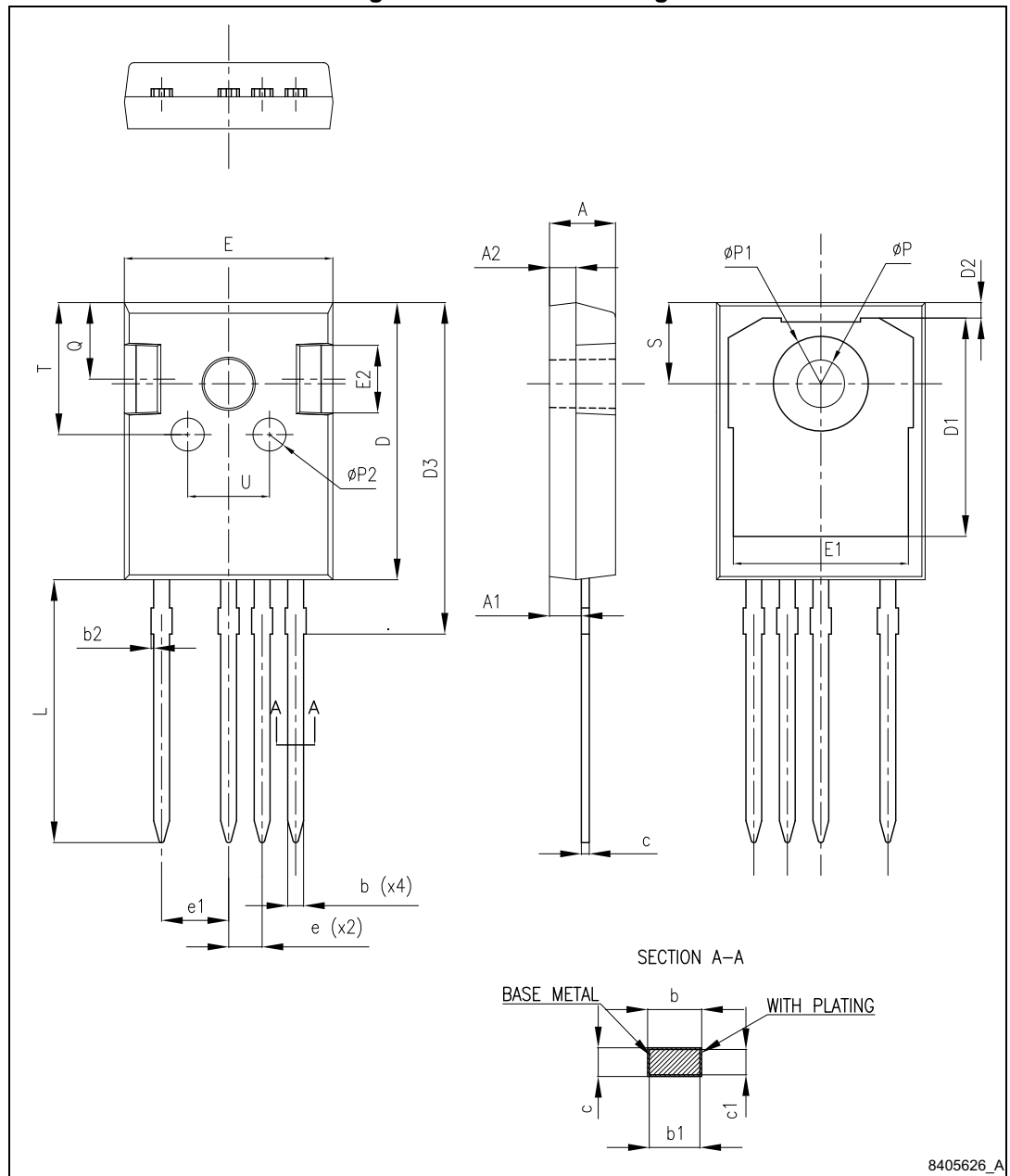


## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 TO247-4, STW56N65M2-4

Figure 20. TO247-4 drawing



8405626\_A

Table 9. TO247-4 mechanical data

| Dim. | mm.   |       |       |
|------|-------|-------|-------|
|      | Min.  | Typ.  | Max.  |
| A    | 4.90  | 5.00  | 5.10  |
| A1   | 2.31  | 2.41  | 2.51  |
| A2   | 1.90  | 2.00  | 2.10  |
| b    | 1.16  |       | 1.29  |
| b1   | 1.15  | 1.20  | 1.25  |
| b2   | 0     |       | 0.20  |
| c    | 0.59  |       | 0.66  |
| c1   | 0.58  | 0.60  | 0.62  |
| D    | 20.90 | 21.00 | 21.10 |
| D1   | 16.25 | 16.55 | 16.85 |
| D2   | 1.05  | 1.20  | 1.35  |
| D3   | 24.97 | 25.12 | 25.27 |
| E    | 15.70 | 15.80 | 15.90 |
| E1   | 13.10 | 13.30 | 13.50 |
| E2   | 4.90  | 5.00  | 5.10  |
| E3   | 2.40  | 2.50  | 2.60  |
| e    | 2.44  | 2.54  | 2.64  |
| e1   | 4.98  | 5.08  | 5.18  |
| L    | 19.80 | 19.92 | 20.10 |
| P    | 3.50  | 3.60  | 3.70  |
| P1   |       |       | 7.40  |
| P2   | 2.40  | 2.50  | 2.60  |
| Q    | 5.60  |       | 6.00  |
| S    |       | 6.15  |       |
| T    | 9.80  |       | 10.20 |
| U    | 6.00  |       | 6.40  |

## 5 Revision history

Table 10. Document revision history

| Date        | Revision | Changes          |
|-------------|----------|------------------|
| 15-Dec-2014 | 1        | Initial release. |

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